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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Not For New Designs
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I ² C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	55
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	3K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 5.5V
Data Converters	A/D 12x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LFQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f212b8sdfp-v2

Table 1.2 Specifications for R8C/2A Group (2)

Item	Function	Specification
Serial Interface	UART0, UART1, UART2	Clock synchronous serial I/O/UART × 3
Clock Synchronous Serial I/O with Chip Select (SSU)		1 (shared with I ² C-bus)
I ² C bus ⁽¹⁾		1 (shared with SSU)
LIN Module		Hardware LIN: 1 (timer RA, UART0)
A/D Converter		10-bit resolution × 12 channels, includes sample and hold function
D/A Converter		8-bit resolution × 2 circuits
Flash Memory		• Programming and erasure voltage: VCC = 2.7 to 5.5 V • Programming and erasure endurance: 100 times • Program security: ROM code protect, ID code check • Debug functions: On-chip debug, on-board flash rewrite function
Operating Frequency/Supply Voltage		f(XIN) = 20 MHz (VCC = 3.0 to 5.5 V) f(XIN) = 10 MHz (VCC = 2.7 to 5.5 V) f(XIN) = 5 MHz (VCC = 2.2 to 5.5 V)
Current consumption		12 mA (VCC = 5.0 V, f(XIN) = 20 MHz) 5.5 mA (VCC = 3.0 V, f(XIN) = 10 MHz) 2.1 μA (VCC = 3.0 V, wait mode (f(XCIN) = 32 kHz)) 0.65 μA (VCC = 3.0 V, stop mode)
Operating Ambient Temperature		-20 to 85°C (N version) -40 to 85°C (D version) ⁽²⁾ -20 to 105°C (Y version) ⁽³⁾
Package		64-pin LQFP • Package code: PLQP0064KB-A (previous code: 64P6Q-A) • Package code: PLQP0064GA-A (previous code: 64P6U-A) 64-pin FLGA • Package code: PTLG0064JA-A (previous code: 64F0G)

NOTES:

1. I²C bus is a trademark of Koninklijke Philips Electronics N. V.
2. Specify the D version if D version functions are to be used.
3. Please contact Renesas Technology sales offices for the Y version.

Table 1.4 Specifications for R8C/2B Group (2)

Item	Function	Specification
Serial Interface	UART0, UART1, UART2	Clock synchronous serial I/O/UART × 3
Clock Synchronous Serial I/O with Chip Select (SSU)		1 (shared with I ² C-bus)
I ² C bus ⁽¹⁾		1 (shared with SSU)
LIN Module		Hardware LIN: 1 (timer RA, UART0)
A/D Converter		10-bit resolution × 12 channels, includes sample and hold function
D/A Converter		8-bit resolution × 2 circuits
Flash Memory		• Programming and erasure voltage: VCC = 2.7 to 5.5 V • Programming and erasure endurance: 10,000 times (data flash) 1,000 times (program ROM) • Program security: ROM code protect, ID code check • Debug functions: On-chip debug, on-board flash rewrite function
Operating Frequency/Supply Voltage		f(XIN) = 20 MHz (VCC = 3.0 to 5.5 V) f(XIN) = 10 MHz (VCC = 2.7 to 5.5 V) f(XIN) = 5 MHz (VCC = 2.2 to 5.5 V)
Current consumption		12 mA (VCC = 5.0 V, f(XIN) = 20 MHz) 5.5 mA (VCC = 3.0 V, f(XIN) = 10 MHz) 2.1 μA (VCC = 3.0 V, wait mode (f(XCIN) = 32 kHz)) 0.65 μA (VCC = 3.0 V, stop mode)
Operating Ambient Temperature		-20 to 85°C (N version) -40 to 85°C (D version) ⁽²⁾ -20 to 105°C (Y version) ⁽³⁾
Package		64-pin LQFP • Package code: PLQP0064KB-A (previous code: 64P6Q-A) • Package code: PLQP0064GA-A (previous code: 64P6U-A) 64-pin FLGA • Package code: PTLG0064JA-A (previous code: 64F0G)

NOTES:

1. I²C bus is a trademark of Koninklijke Philips Electronics N. V.
2. Specify the D version if D version functions are to be used.
3. Please contact Renesas Technology sales offices for the Y version.

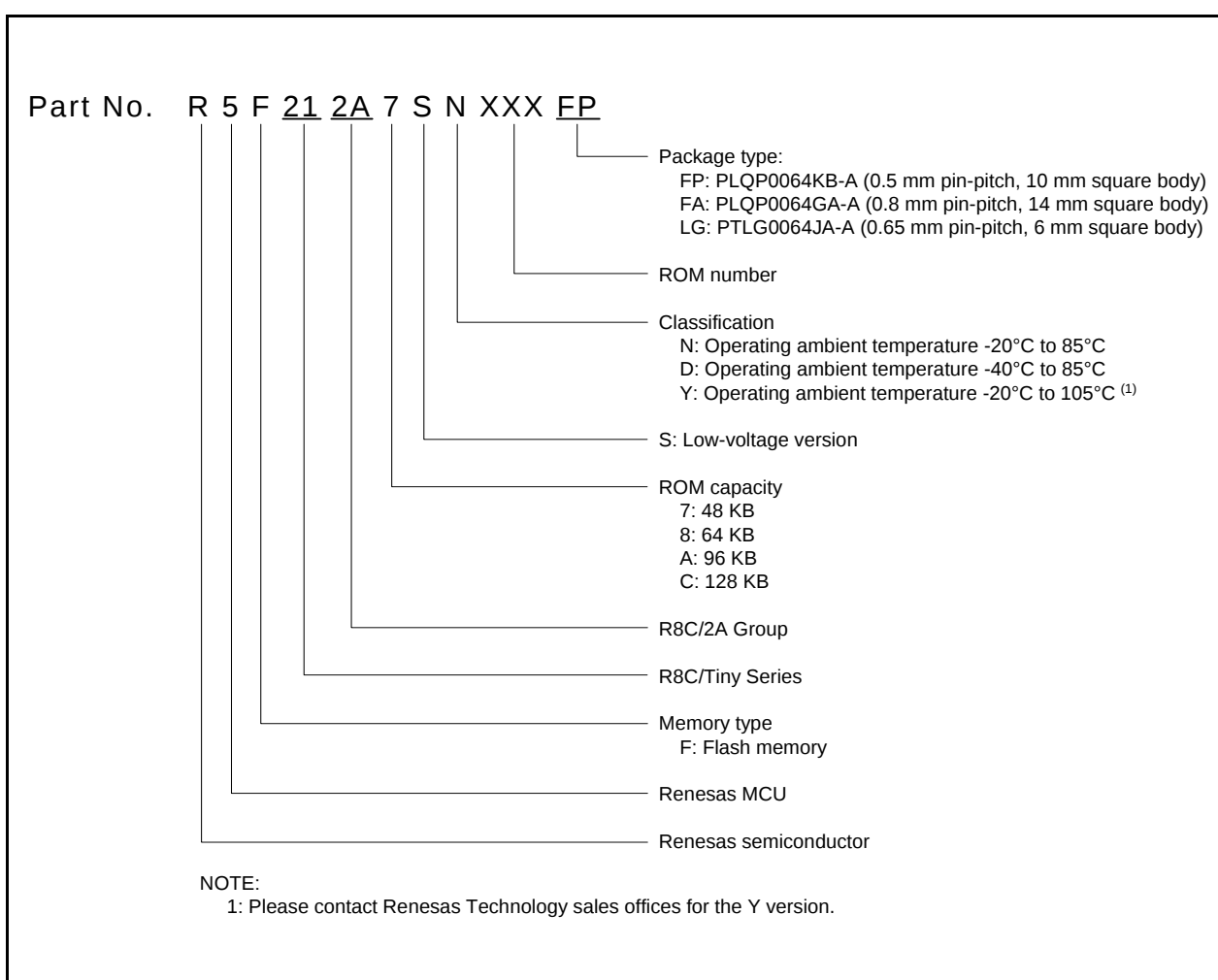


Figure 1.1 Part Number, Memory Size, and Package of R8C/2A Group

Table 1.6 Product List for R8C/2B Group

Current of Nov. 2007

Part No.	ROM Capacity		RAM Capacity	Package Type	Remarks		
	Program ROM	Data flash					
R5F212B7SNFP	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PLQP0064KB-A	N version		
R5F212B7SNFA	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PLQP0064GA-A			
R5F212B7SNLG	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PTLG0064JA-A			
R5F212B8SNFP	64 Kbytes	1 Kbyte × 2	3 Kbytes	PLQP0064KB-A			
R5F212B8SNFA	64 Kbytes	1 Kbyte × 2	3 Kbytes	PLQP0064GA-A			
R5F212B8SNLG	64 Kbytes	1 Kbyte × 2	3 Kbytes	PTLG0064JA-A			
R5F212BASNFP	96 Kbytes	1 Kbyte × 2	7 Kbytes	PLQP0064KB-A			
R5F212BASNFA	96 Kbytes	1 Kbyte × 2	7 Kbytes	PLQP0064GA-A			
R5F212BASNLG	96 Kbytes	1 Kbyte × 2	7 Kbytes	PTLG0064JA-A			
R5F212BCSNFP	128 Kbytes	1 Kbyte × 2	7.5 Kbytes	PLQP0064KB-A			
R5F212BCSNFA	128 Kbytes	1 Kbyte × 2	7.5 Kbytes	PLQP0064GA-A			
R5F212BCSNLG	128 Kbytes	1 Kbyte × 2	7.5 Kbytes	PTLG0064JA-A			
R5F212B7SDFP	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PLQP0064KB-A	D version		
R5F212B7SDFA	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PLQP0064GA-A			
R5F212B8SDFP	64 Kbytes	1 Kbyte × 2	3 Kbytes	PLQP0064KB-A			
R5F212B8SDFA	64 Kbytes	1 Kbyte × 2	3 Kbytes	PLQP0064GA-A			
R5F212BASDFP	96 Kbytes	1 Kbyte × 2	7 Kbytes	PLQP0064KB-A			
R5F212BASDFA	96 Kbytes	1 Kbyte × 2	7 Kbytes	PLQP0064GA-A			
R5F212BCSDFP	128 Kbytes	1 Kbyte × 2	7.5 Kbytes	PLQP0064KB-A			
R5F212BCSDFA	128 Kbytes	1 Kbyte × 2	7.5 Kbytes	PLQP0064GA-A			
R5F212B7SNXXXFP	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PLQP0064KB-A	N version	Factory programming product ⁽¹⁾	
R5F212B7SNXXXFA	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PLQP0064GA-A			
R5F212B7SNXXXLG	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PTLG0064JA-A			
R5F212B8SNXXXFP	64 Kbytes	1 Kbyte × 2	3 Kbytes	PLQP0064KB-A			
R5F212B8SNXXXFA	64 Kbytes	1 Kbyte × 2	3 Kbytes	PLQP0064GA-A			
R5F212B8SNXXXLG	64 Kbytes	1 Kbyte × 2	3 Kbytes	PTLG0064JA-A			
R5F212BASNXXXFP	96 Kbytes	1 Kbyte × 2	7 Kbytes	PLQP0064KB-A			
R5F212BASNXXXFA	96 Kbytes	1 Kbyte × 2	7 Kbytes	PLQP0064GA-A			
R5F212BASNXXXLG	96 Kbytes	1 Kbyte × 2	7 Kbytes	PTLG0064JA-A			
R5F212BCSNXXXFP	128 Kbytes	1 Kbyte × 2	7.5 Kbytes	PLQP0064KB-A			
R5F212BCSNXXXFA	128 Kbytes	1 Kbyte × 2	7.5 Kbytes	PLQP0064GA-A			
R5F212BCSNXXXLG	128 Kbytes	1 Kbyte × 2	7.5 Kbytes	PTLG0064JA-A			
R5F212B7SDXXXFP	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PLQP0064KB-A	D version		
R5F212B7SDXXXFA	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PLQP0064GA-A			
R5F212B8SDXXXFP	64 Kbytes	1 Kbyte × 2	3 Kbytes	PLQP0064KB-A			
R5F212B8SDXXXFA	64 Kbytes	1 Kbyte × 2	3 Kbytes	PLQP0064GA-A			
R5F212BASDXXXFP	96 Kbytes	1 Kbyte × 2	7 Kbytes	PLQP0064KB-A			
R5F212BASDXXXFA	96 Kbytes	1 Kbyte × 2	7 Kbytes	PLQP0064GA-A			
R5F212BCSDXXXFP	128 Kbytes	1 Kbyte × 2	7.5 Kbytes	PLQP0064KB-A			
R5F212BCSDXXXFA	128 Kbytes	1 Kbyte × 2	7.5 Kbytes	PLQP0064GA-A			

NOTE:

1. The user ROM is programmed before shipment.

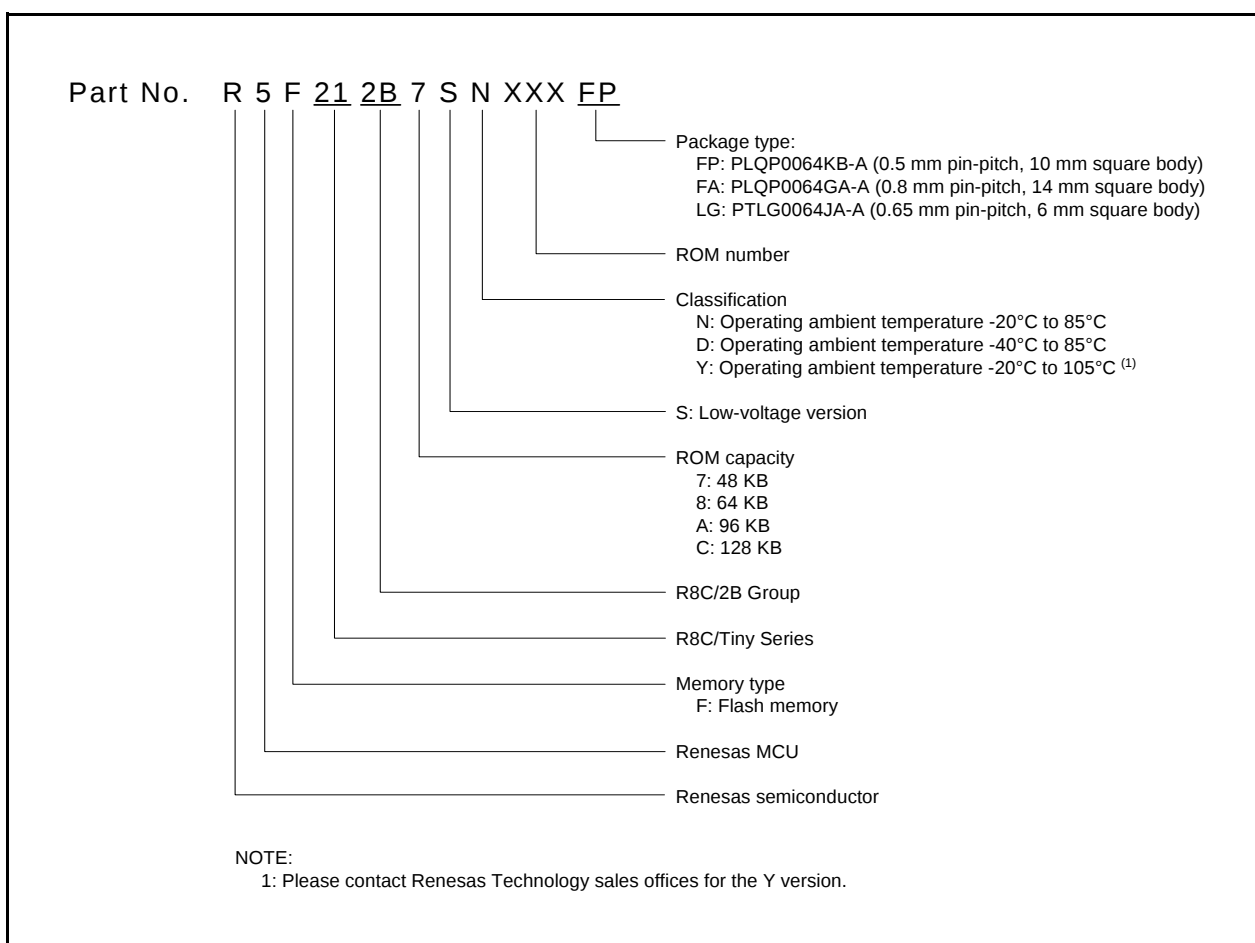


Figure 1.2 Part Number, Memory Size, and Package of R8C/2B Group

Table 1.8 Pin Name Information by Pin Number (2)

Pin Number	Control Pin	Port	I/O Pin Functions for of Peripheral Modules					
			Interrupt	Timer	Serial Interface	SSU	I ² C bus	A/D Converter, D/A Converter
46		P1_3	$\overline{\text{KI3}}$					AN11
47		P1_2	$\overline{\text{KI2}}$					AN10
48		P1_1	$\overline{\text{KI1}}$					AN9
49		P1_0	$\overline{\text{KI0}}$					AN8
50		P0_0						AN7
51		P0_1						AN6
52		P0_2						AN5
53		P0_3						AN4
54		P0_4						AN3
55		P6_2						
56		P6_1						
57		P0_5			CLK1			AN2
58		P0_6						AN1/DA0
59	VSS/AVSS							
60		P0_7						AN0/DA1
61	VREF							
62	VCC/AVCC							
63		P3_7				SSO		
64		P3_5				SSCK	SCL	

2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU Registers. The CPU contains 13 registers. R0, R1, R2, R3, A0, A1, and FB configure a register bank. There are two sets of register bank.

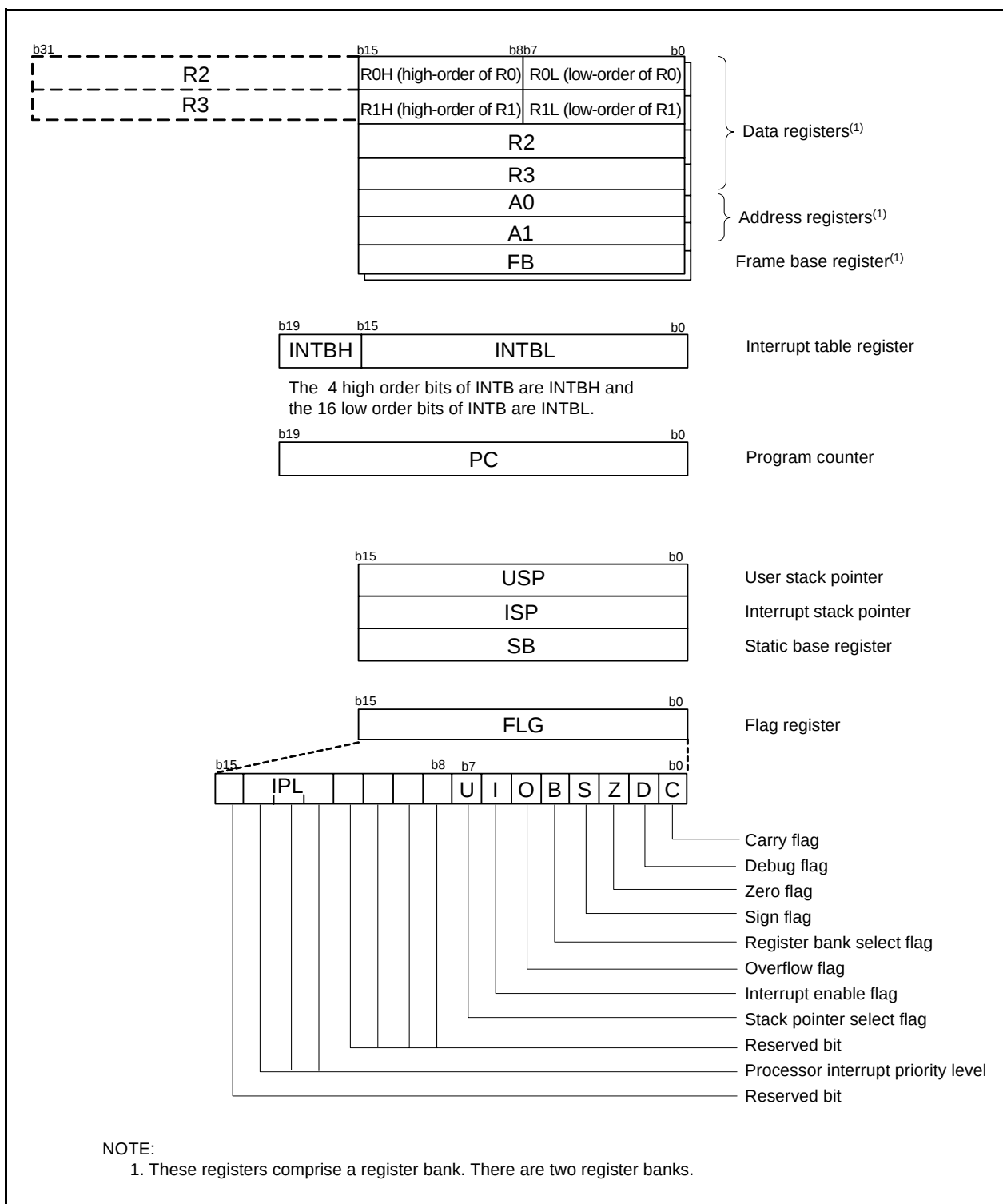


Figure 2.1 CPU Registers

3.2 R8C/2B Group

Figure 3.2 is a Memory Map of R8C/2B Group. The R8C/2B group has 1 Mbyte of address space from addresses 00000h to FFFFFh.

The internal ROM (program ROM) is allocated lower addresses, beginning with address 0FFFFh. For example, a 48-Kbyte internal ROM area is allocated addresses 04000h to 0FFFFh.

The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. They store the starting address of each interrupt routine.

The internal ROM (data flash) is allocated addresses 02400h to 02BFFh.

The internal RAM area is allocated higher addresses, beginning with address 00400h. For example, a 2.5-Kbyte internal RAM is allocated addresses 00400h to 00DFFh. The internal RAM is used not only for storing data but also for calling subroutines and as stacks when interrupt requests are acknowledged.

Special function registers (SFRs) are allocated addresses 00000h to 002FFh. The peripheral function control registers are allocated here. All addresses within the SFR, which have nothing allocated are reserved for future use and cannot be accessed by users.

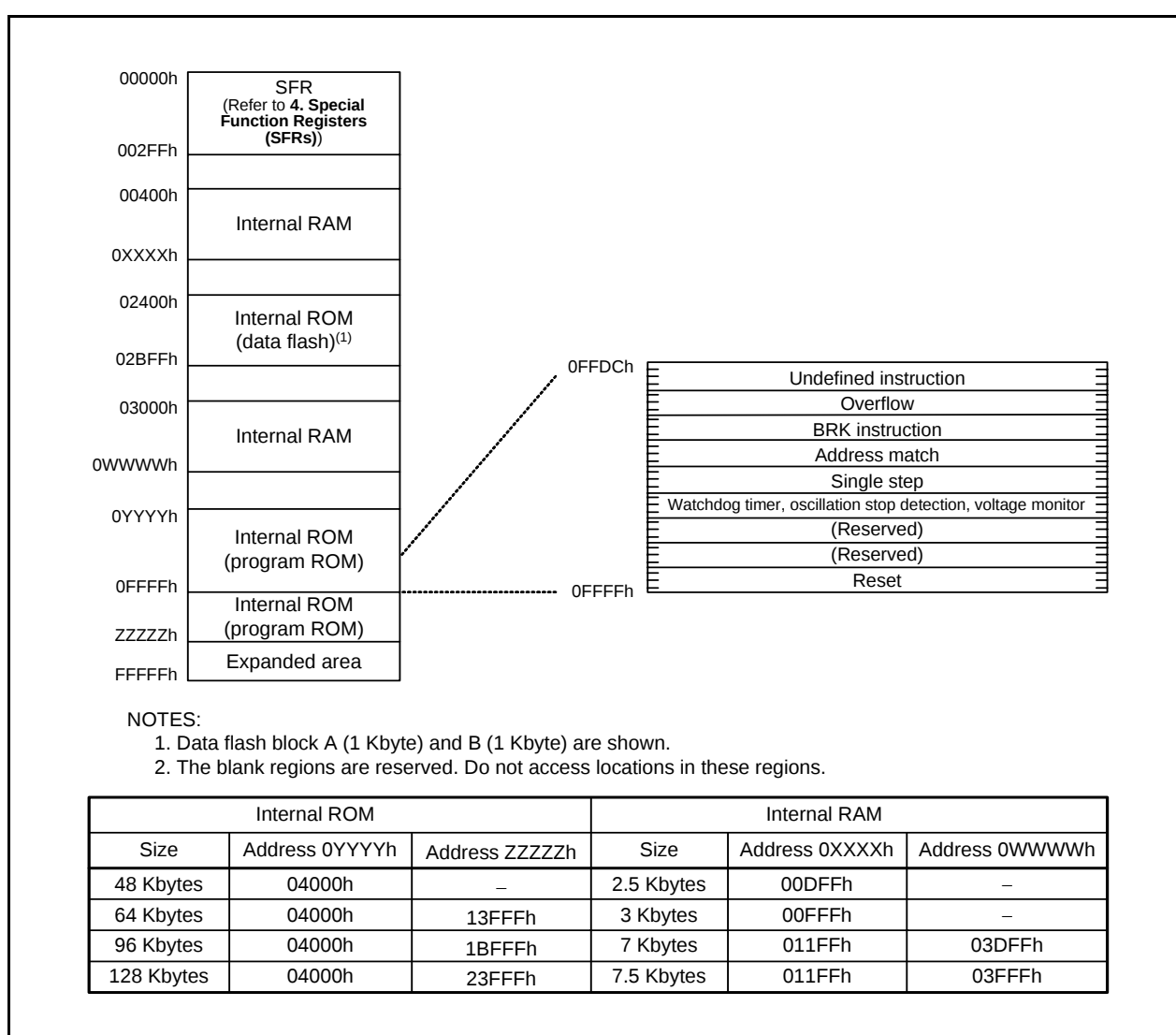


Figure 3.2 Memory Map of R8C/2B Group

Table 4.4 SFR Information (4)⁽¹⁾

Address	Register	Symbol	After reset
00C0h			
00C1h			
00C2h			
00C3h			
00C4h			
00C5h			
00C6h			
00C7h			
00C8h			
00C9h			
00CAh			
00CBh			
00CCh			
00CDh			
00CEh			
00CFh			
00D0h			
00D1h			
00D2h			
00D3h			
00D4h			
00D5h			
00D6h			
00D7h			
00D8h	D/A Register 0	DA0	00h
00D9h			
00DAh	D/A Register 1	DA1	00h
00DBh			
00DCh	D/A Control Register	DACON	00h
00DDh			
00DEh			
00DFh			
00E0h	Port P0 Register	P0	XXh
00E1h	Port P1 Register	P1	XXh
00E2h	Port P0 Direction Register	PD0	00h
00E3h	Port P1 Direction Register	PD1	00h
00E4h	Port P2 Register	P2	XXh
00E5h	Port P3 Register	P3	XXh
00E6h	Port P2 Direction Register	PD2	00h
00E7h	Port P3 Direction Register	PD3	00h
00E8h	Port P4 Register	P4	XXh
00E9h	Port P5 Register	P5	XXh
00EAh	Port P4 Direction Register	PD4	00h
00EBh	Port P5 Direction Register	PD5	00h
00ECh	Port P6 Register	P6	XXh
00EDh			
00EEh	Port P6 Direction Register	PD6	00h
00EFh			
00F0h			
00F1h			
00F2h			
00F3h			
00F4h	Port P2 Drive Capacity Control Register	P2DRR	00h
00F5h	UART1 Function Select Register	U1SR	000000XXb
00F6h			
00F7h			
00F8h	Port Mode Register	PMR	00h
00F9h	External Input Enable Register	INTEN	00h
00FAh	INT Input Filter Select Register	INTF	00h
00FBh	Key Input Enable Register	KIEN	00h
00FCh	Pull-Up Control Register 0	PUR0	00h
00FDh	Pull-Up Control Register 1	PUR1	XX000000b
00FEh			
00FFh			

X: Undefined

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

Table 4.8 SFR Information (8)⁽¹⁾

Address	Register	Symbol	After reset
01C0h			
01C1h			
01C2h			
01C3h			
01C4h			
01C5h			
01C6h			
01C7h			
01C8h			
01C9h			
01CAh			
01CBh			
01CCh			
01CDh			
01CEh			
01CFh			
01D0h			
01D1h			
01D2h			
01D3h			
01D4h			
01D5h			
01D6h			
01D7h			
01D8h			
01D9h			
01DAh			
01DBh			
01DCh			
01DDh			
01DEh			
01DFh			
01E0h			
01E1h			
01E2h			
01E3h			
01E4h			
01E5h			
01E6h			
01E7h			
01E8h			
01E9h			
01EAh			
01EBh			
01ECh			
01EDh			
01EEh			
01EFh			
01F0h			
01F1h			
01F2h			
01F3h			
01F4h			
01F5h			
01F6h			
01F7h			
01F8h			
01F9h			
01FAh			
01FBh			
01FCh			
01FDh			
01FEh			
01FFh			

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

Table 5.5 Flash Memory (Program ROM) Electrical Characteristics

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
–	Program/erase endurance ⁽²⁾	R8C/2A Group	100 ⁽³⁾	–	–	times
		R8C/2B Group	1,000 ⁽³⁾	–	–	times
–	Byte program time		–	50	400	μs
–	Block erase time		–	0.4	9	s
t _d (SR-SUS)	Time delay from suspend request until suspend		–	–	97+CPU clock × 6 cycles	μs
–	Interval from erase start/restart until following suspend request		650	–	–	μs
–	Interval from program start/restart until following suspend request		0	–	–	ns
–	Time from suspend until program/erase restart		–	–	3+CPU clock × 4 cycles	μs
–	Program, erase voltage		2.7	–	5.5	V
–	Read voltage		2.2	–	5.5	V
–	Program, erase temperature		0	–	60	°C
–	Data hold time ⁽⁷⁾	Ambient temperature = 55°C	20	–	–	year

NOTES:

1. V_{CC} = 2.7 to 5.5 V at T_{opr} = 0 to 60°C, unless otherwise specified.
2. Definition of programming/erasure endurance
The programming and erasure endurance is defined on a per-block basis.
If the programming and erasure endurance is n (n = 100 or 10,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
3. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
4. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erase count of each block and limit the number of erase operations to a certain number.
5. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
6. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
7. The data hold time includes time that the power supply is off or the clock is not supplied.

Table 5.10 Power-on Reset Circuit, Voltage Monitor 0 Reset Electrical Characteristics⁽³⁾

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V _{por1}	Power-on reset valid voltage ⁽⁴⁾		–	–	0.1	V
V _{por2}	Power-on reset or voltage monitor 0 reset valid voltage		0	–	V _{det0}	V
tr _{th}	External power V _{CC} rise gradient ⁽²⁾		20	–	–	mV/msec

NOTES:

1. The measurement condition is T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.
2. This condition (external power V_{CC} rise gradient) does not apply if V_{CC} ≥ 1.0 V.
3. To use the power-on reset function, enable voltage monitor 0 reset by setting the LVD0ON bit in the OFS register to 0, the VW0C0 and VW0C6 bits in the VW0C register to 1 respectively, and the VCA25 bit in the VCA2 register to 1.
4. t_{w(por1)} indicates the duration the external power V_{CC} must be held below the effective voltage (V_{por1}) to enable a power on reset. When turning on the power for the first time, maintain t_{w(por1)} for 30 s or more if -20°C ≤ T_{opr} ≤ 85°C, maintain t_{w(por1)} for 3,000 s or more if -40°C ≤ T_{opr} < -20°C.

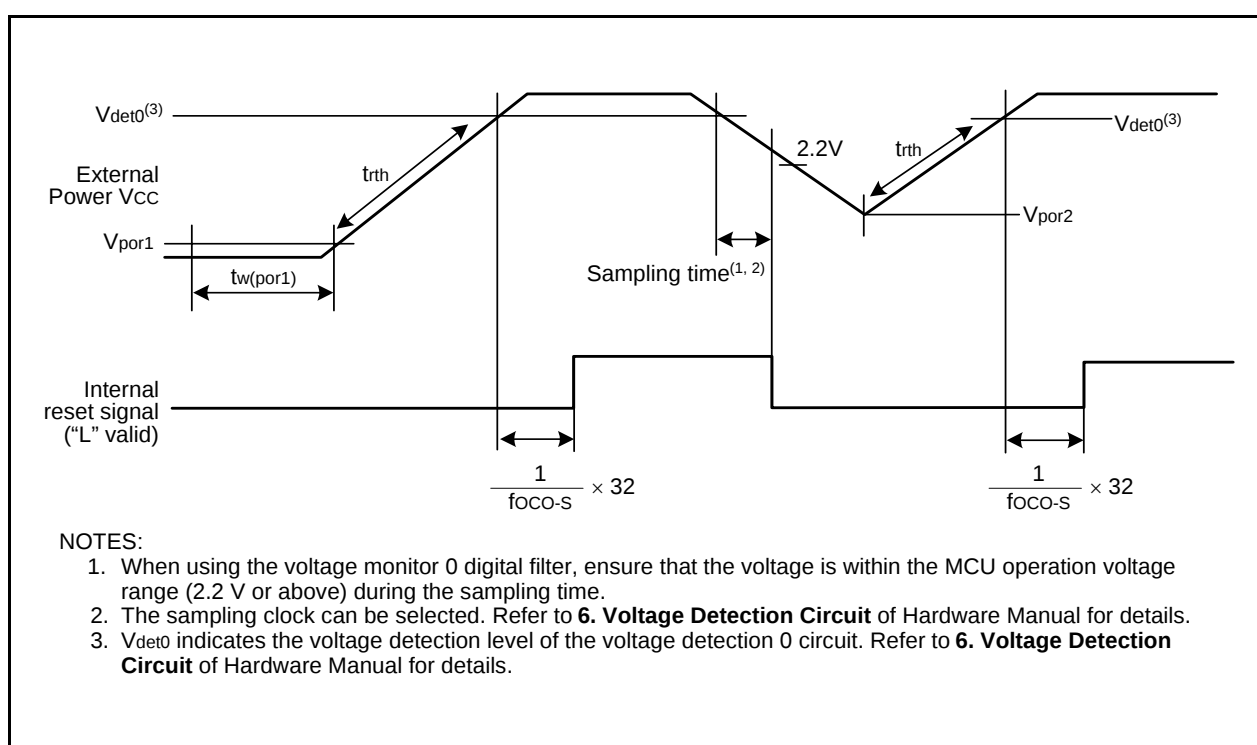
**Figure 5.3 Power-on Reset Circuit Electrical Characteristics**

Table 5.14 Timing Requirements of Clock Synchronous Serial I/O with Chip Select⁽¹⁾

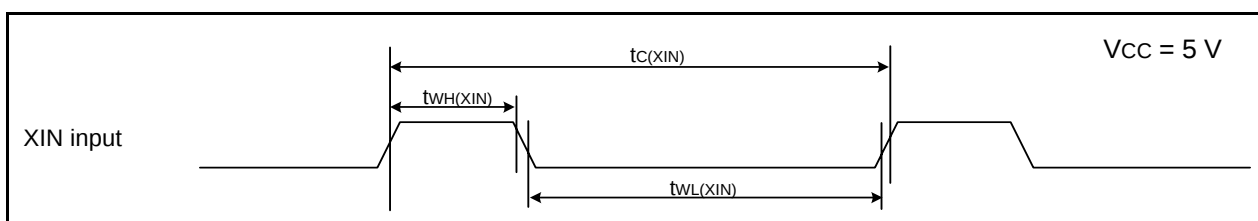
Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
tsucyc	SSCK clock cycle time			4	–	–	tcyc ⁽²⁾
t _{HI}	SSCK clock "H" width			0.4	–	0.6	tsucyc
t _{LO}	SSCK clock "L" width			0.4	–	0.6	tsucyc
trise	SSCK clock rising time	Master		–	–	1	tcyc ⁽²⁾
		Slave		–	–	1	μs
tfall	SSCK clock falling time	Master		–	–	1	tcyc ⁽²⁾
		Slave		–	–	1	μs
tsu	SSO, SSI data input setup time			100	–	–	ns
t _H	SSO, SSI data input hold time			1	–	–	tcyc ⁽²⁾
t _{LEAD}	$\overline{\text{SCS}}$ setup time	Slave		1tcyc + 50	–	–	ns
t _{LAG}	$\overline{\text{SCS}}$ hold time	Slave		1tcyc + 50	–	–	ns
t _{OD}	SSO, SSI data output delay time			–	–	1	tcyc ⁽²⁾
t _{SA}	SSI slave access time		2.7 V ≤ V _{CC} ≤ 5.5 V	–	–	1.5tcyc + 100	ns
			2.2 V ≤ V _{CC} < 2.7 V	–	–	1.5tcyc + 200	ns
t _{OR}	SSI slave out open time		2.7 V ≤ V _{CC} ≤ 5.5 V	–	–	1.5tcyc + 100	ns
			2.2 V ≤ V _{CC} < 2.7 V	–	–	1.5tcyc + 200	ns

NOTES:

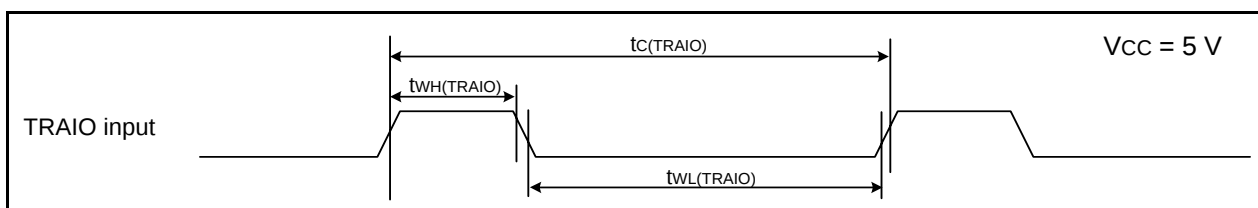
1. V_{CC} = 2.2 to 5.5 V, V_{SS} = 0 V at T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.
2. 1tcyc = 1/f₁(s)

Timing Requirements**(Unless Otherwise Specified: $V_{CC} = 5\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_{op} = 25^\circ\text{C}$) [$V_{CC} = 5\text{ V}$]****Table 5.18 XIN Input, XCIN Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XIN)}$	XIN input cycle time	50	—	ns
$t_{WH(XIN)}$	XIN input "H" width	25	—	ns
$t_{WL(XIN)}$	XIN input "L" width	25	—	ns
$t_{c(XCIN)}$	XCIN input cycle time	14	—	μs
$t_{WH(XCIN)}$	XCIN input "H" width	7	—	μs
$t_{WL(XCIN)}$	XCIN input "L" width	7	—	μs

**Figure 5.8 XIN Input and XCIN Input Timing Diagram when $V_{CC} = 5\text{ V}$** **Table 5.19 TRAIO Input, $\overline{\text{INT1}}$ Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input cycle time	100	—	ns
$t_{WH(TRAIO)}$	TRAIO input "H" width	40	—	ns
$t_{WL(TRAIO)}$	TRAIO input "L" width	40	—	ns

**Figure 5.9 TRAIO Input and $\overline{\text{INT1}}$ Input Timing Diagram when $V_{CC} = 5\text{ V}$** **Table 5.20 TRFI Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRFI)}$	TRFI input cycle time	400 ⁽¹⁾	—	ns
$t_{WH(TRFI)}$	TRFI input "H" width	200 ⁽²⁾	—	ns
$t_{WL(TRFI)}$	TRFI input "L" width	200 ⁽²⁾	—	ns

NOTES:

1. When using timer RF input capture mode, adjust the cycle time to $(1/\text{timer RF count source frequency} \times 3)$ or above.
2. When using timer RF input capture mode, adjust the pulse width to $(1/\text{timer RF count source frequency} \times 1.5)$ or above.

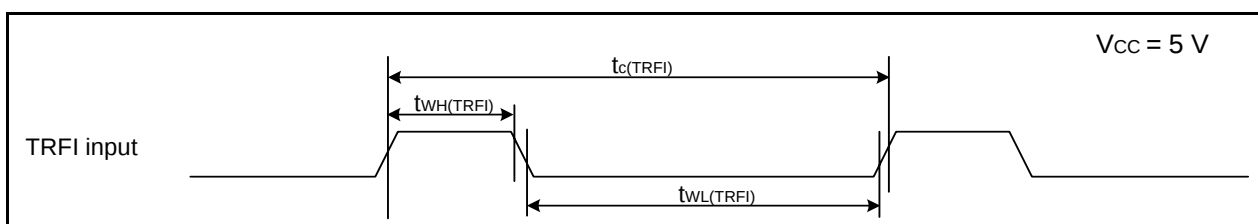
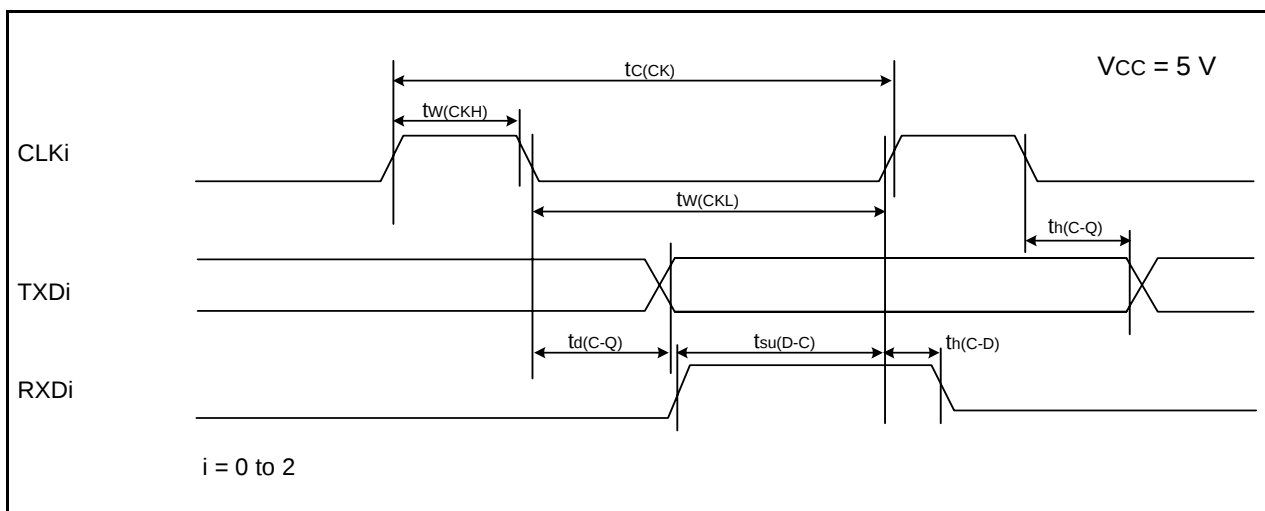
**Figure 5.10 TRFI Input Timing Diagram when $V_{CC} = 5\text{ V}$**

Table 5.21 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	200	—	ns
$t_{w(CKH)}$	CLKi input "H" width	100	—	ns
$t_{w(CKL)}$	CLKi input "L" width	100	—	ns
$t_{d(C-Q)}$	TXDi output delay time	—	50	ns
$t_{h(C-Q)}$	TXDi hold time	0	—	ns
$t_{su(D-C)}$	RXDi input setup time	50	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	ns

 $i = 0 \text{ to } 2$ **Figure 5.11 Serial Interface Timing Diagram when Vcc = 5 V****Table 5.22 External Interrupt $\overline{INTi}$ ($i = 0, 2, 3$) Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{INT0}$ input "H" width	250 ⁽¹⁾	—	ns
$t_{w(INL)}$	$\overline{INT0}$ input "L" width	250 ⁽²⁾	—	ns

NOTES:

1. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input HIGH width of either (1/digital filter clock frequency $\times$ 3) or the minimum value of standard, whichever is greater.
2. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input LOW width of either (1/digital filter clock frequency $\times$ 3) or the minimum value of standard, whichever is greater.

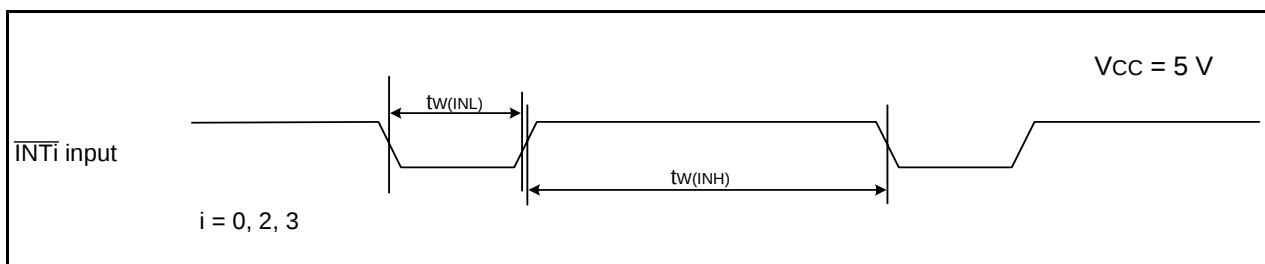
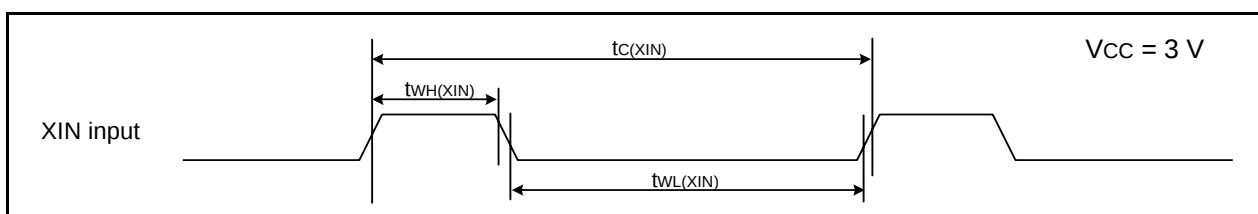
**Figure 5.12 External Interrupt $\overline{INTi}$ Input Timing Diagram when Vcc = 5 V**

Table 5.24 Electrical Characteristics (4) [V_{CC} = 3 V]
(T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.)

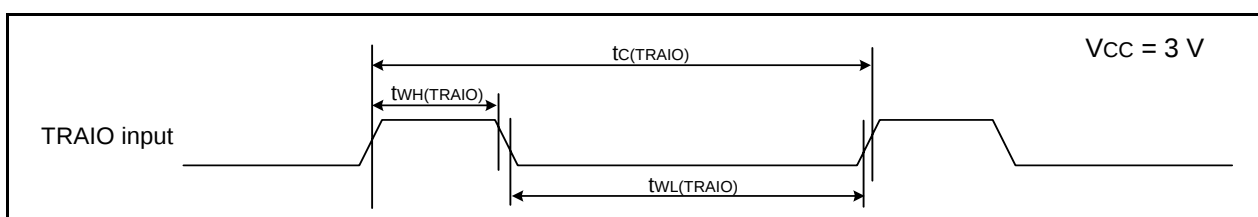
Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
I _{CC}	Power supply current (V _{CC} = 2.7 to 3.3 V) Single-chip mode, output pins are open, other pins are V _{SS}	High-speed clock mode	—	5.5	—	mA
				2	—	
		High-speed on-chip oscillator mode	—	5.5	11	mA
				2.2	—	
		Low-speed on-chip oscillator mode	—	145	400	μA
				145	400	
		Low-speed clock mode	—	30	—	μA
				—	—	
		Wait mode	—	28	85	μA
				17	50	
				3.3	—	
				2.1	—	
		Stop mode	—	0.65	3.0	μA
				1.65	—	

Timing requirements**(Unless Otherwise Specified: $V_{CC} = 3\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_{op} = 25^\circ\text{C}$) [$V_{CC} = 3\text{ V}$]****Table 5.25 XIN Input, XCIN Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XIN)}$	XIN input cycle time	100	–	ns
$t_{WH(XIN)}$	XIN input “H” width	40	–	ns
$t_{WL(XIN)}$	XIN input “L” width	40	–	ns
$t_{c(XCIN)}$	XCIN input cycle time	14	–	μs
$t_{WH(XCIN)}$	XCIN input “H” width	7	–	μs
$t_{WL(XCIN)}$	XCIN input “L” width	7	–	μs

**Figure 5.13 XIN Input and XCIN Input Timing Diagram when $V_{CC} = 3\text{ V}$** **Table 5.26 TRAIO Input, $\overline{\text{INT1}}$ Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input cycle time	300	–	ns
$t_{WH(TRAIO)}$	TRAIO input “H” width	120	–	ns
$t_{WL(TRAIO)}$	TRAIO input “L” width	120	–	ns

**Figure 5.14 TRAIO Input and $\overline{\text{INT1}}$ Input Timing Diagram when $V_{CC} = 3\text{ V}$** **Table 5.27 TRFI Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRFI)}$	TRFI input cycle time	1200 ⁽¹⁾	–	ns
$t_{WH(TRFI)}$	TRFI input “H” width	600 ⁽²⁾	–	ns
$t_{WL(TRFI)}$	TRFI input “L” width	600 ⁽²⁾	–	ns

NOTES:

1. When using timer RF input capture mode, adjust the cycle time to $(1/\text{timer RF count source frequency} \times 3)$ or above.
2. When using timer RF input capture mode, adjust the pulse width to $(1/\text{timer RF count source frequency} \times 1.5)$ or above.

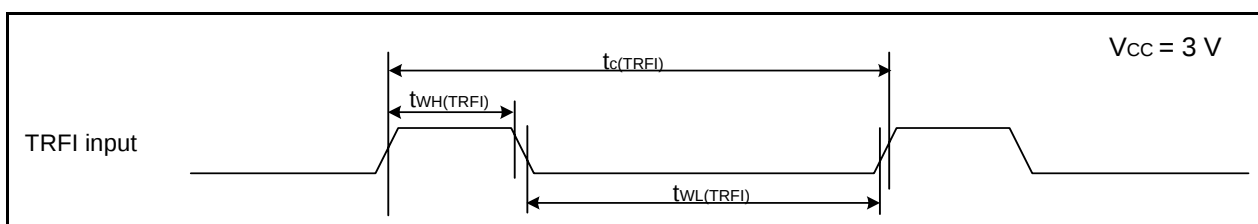
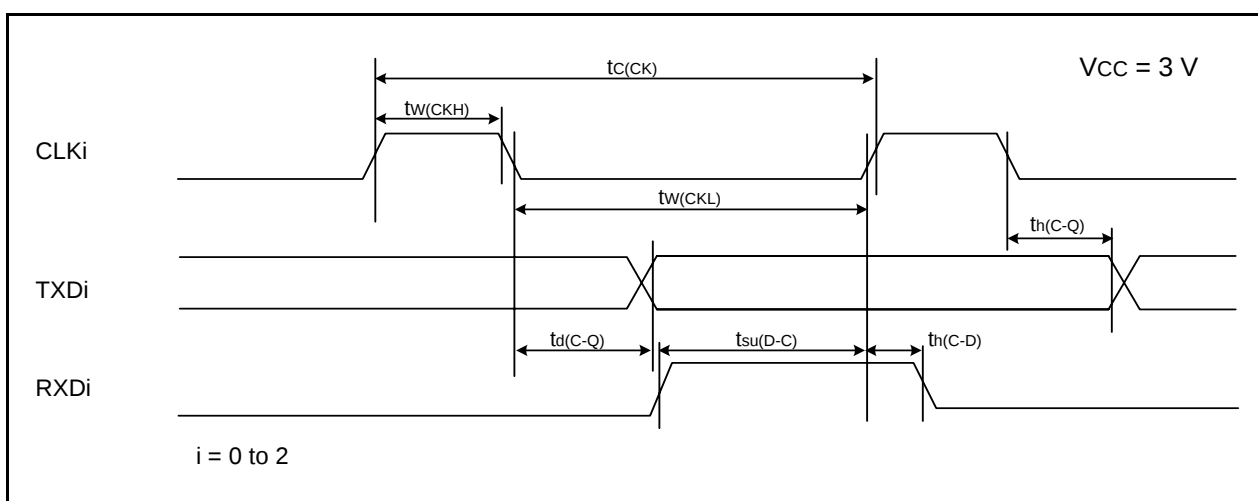
**Figure 5.15 TRFI Input Timing Diagram when $V_{CC} = 3\text{ V}$**

Table 5.28 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	300	—	ns
$t_{w(CKH)}$	CLKi input "H" width	150	—	ns
$t_{w(CKL)}$	CLKi Input "L" width	150	—	ns
$t_{d(C-Q)}$	TXDi output delay time	—	80	ns
$t_{h(C-Q)}$	TXDi hold time	0	—	ns
$t_{su(D-C)}$	RXDi input setup time	70	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	ns

 $i = 0 \text{ to } 2$ **Figure 5.16 Serial Interface Timing Diagram when Vcc = 3 V****Table 5.29 External Interrupt $\overline{INTi}$ ($i = 0, 2, 3$) Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{INT0}$ input "H" width	380 ⁽¹⁾	—	ns
$t_{w(INL)}$	$\overline{INT0}$ input "L" width	380 ⁽²⁾	—	ns

NOTES:

1. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input HIGH width of either (1/digital filter clock frequency $\times 3$) or the minimum value of standard, whichever is greater.
2. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input LOW width of either (1/digital filter clock frequency $\times 3$) or the minimum value of standard, whichever is greater.

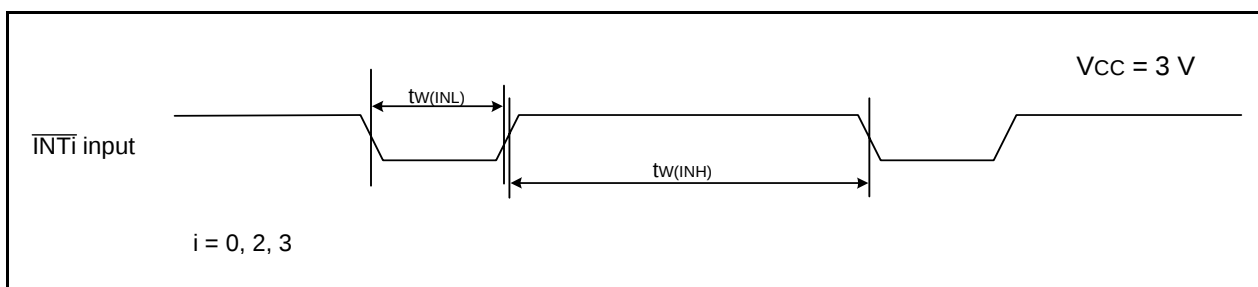
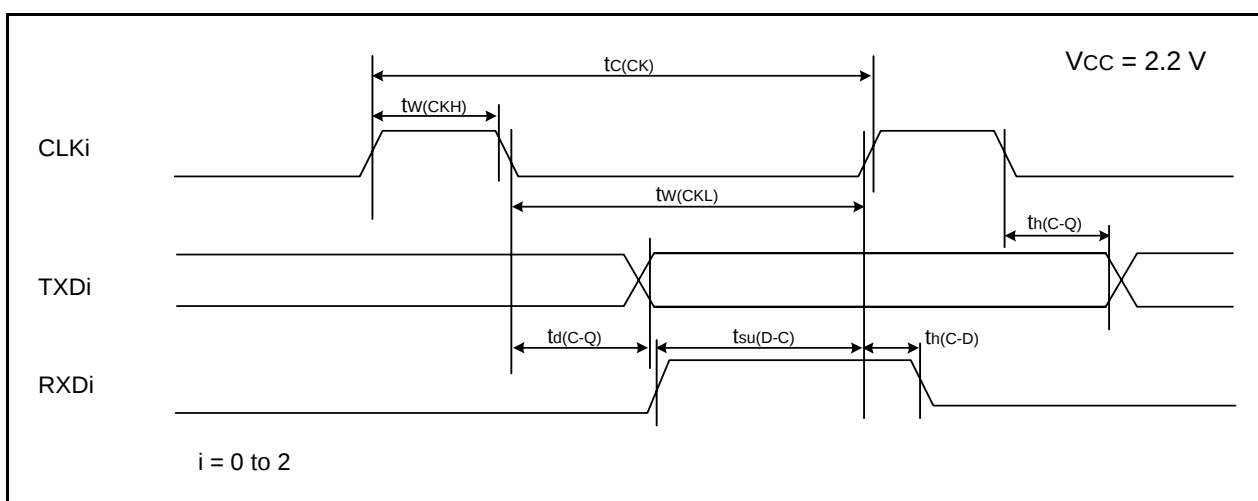
**Figure 5.17 External Interrupt $\overline{INTi}$ Input Timing Diagram when Vcc = 3 V**

Table 5.35 Serial Interface

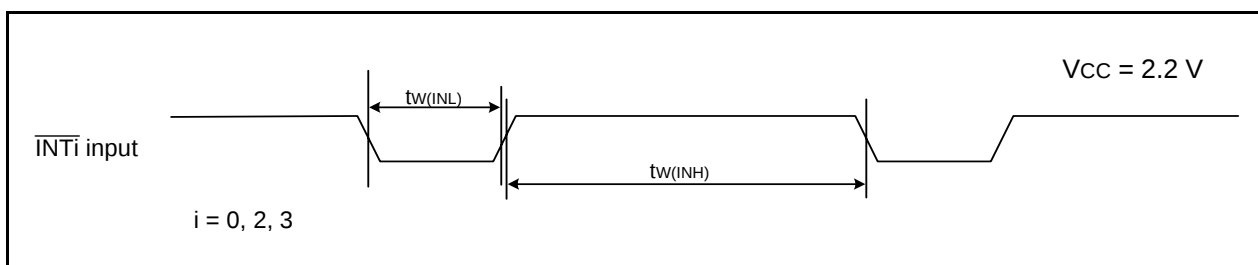
Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	800	—	ns
$t_{w(CKH)}$	CLKi input "H" width	400	—	ns
$t_{w(CKL)}$	CLKi input "L" width	400	—	ns
$t_{d(C-Q)}$	TXDi output delay time	—	200	ns
$t_{h(C-Q)}$	TXDi hold time	0	—	ns
$t_{su(D-C)}$	RXDi input setup time	150	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	ns

 $i = 0 \text{ to } 2$ **Figure 5.21 Serial Interface Timing Diagram when $V_{CC} = 2.2 \text{ V}$** **Table 5.36 External Interrupt $\overline{INTi}$ ($i = 0, 2, 3$) Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{INT0}$ input "H" width	1000 ⁽¹⁾	—	ns
$t_{w(INL)}$	$\overline{INT0}$ input "L" width	1000 ⁽²⁾	—	ns

NOTES:

1. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input HIGH width of either (1/digital filter clock frequency $\times 3$) or the minimum value of standard, whichever is greater.
2. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input LOW width of either (1/digital filter clock frequency $\times 3$) or the minimum value of standard, whichever is greater.

**Figure 5.22 External Interrupt $\overline{INTi}$ Input Timing Diagram when $V_{CC} = 2.2 \text{ V}$**

Package Dimensions

Diagrams showing the latest package dimensions and mounting information are available in the “Packages” section of the Renesas Technology website.

